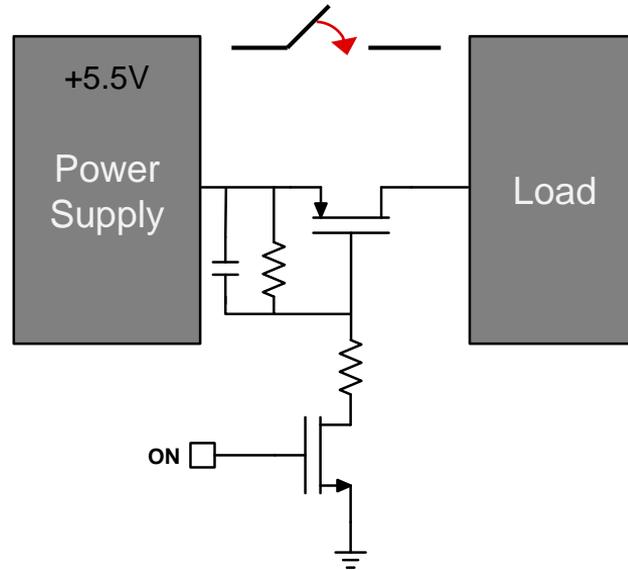


# Load Switch Deep Dive

Texas Instruments

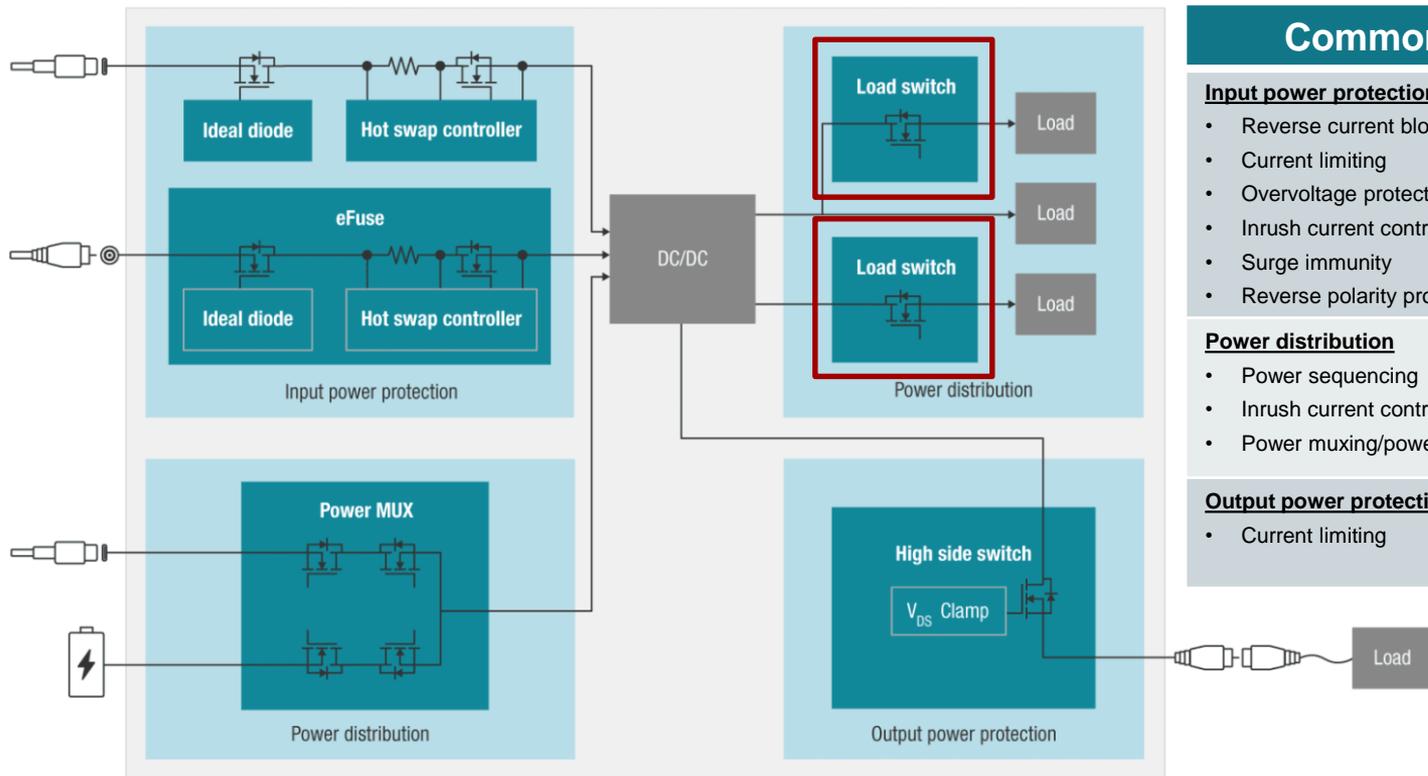
# What is a load switch?

A device that turns DC power OFF and ON to a load



The two main functions a **load switch** can provide to a system is **power protection** and **power distribution**

# Power switches | use cases



## Common design challenges

### Input power protection

- Reverse current blocking
- Current limiting
- Overvoltage protection
- Inrush current control
- Surge immunity
- Reverse polarity protection

### Power distribution

- Power sequencing
- Inrush current control
- Power muxing/power ORing

### Output power protection

- Current limiting

# Load switch overview

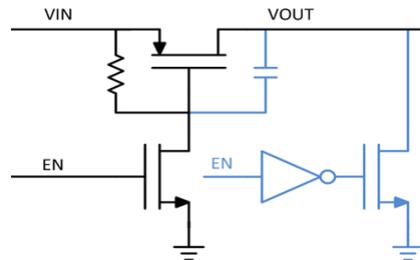
**Extend battery life** by reducing standby leakage current. Turn off unused subsystems w/load switches: WiFi/BT, LCD, SD Card

**Save space** and reduce solution size by integrating discrete circuitry into a load switch (2+ FETs w/Resistors & Capacitors)

**Simplify power sequencing** by implementing point of load control with load switches. Power on/off each rail with GPIO

**Mitigate inrush current damage** to the system with integrated "Soft Start" slew rate /rise time control.

Replace these 7+ components...

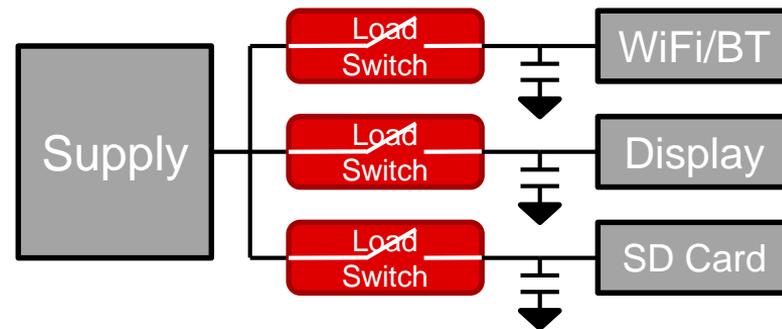


With this 1 device:



Smaller, less components,  
more features, easier design!

Reduce BOM count and board layout



Manage power distribution for subsystems

## Load switch features

### Slew rate control

Adjust the slew rate of your device to meet your systems timing requirements, and limit inrush current

### Power good

Use power good and fault indicators to ensure reliability of your system

### Thermal shutdown

Protects the device from permanent damage from overheating by shutting down

### Short circuit protection

Prevents hard/soft shorts from damaging the device

### Reverse current protection

Prevents current from flowing from the output to the input of the device and damaging it

### Current limit

Limits the current through the device

### Quick output discharge

Discharges the output of the load switch to ground through some resistance

# Inrush current control

- Significant output capacitance causes inrush current
- Load switches **reduce inrush current** by controlling output slew rate & increasing  $T_R$

$$I_{\text{INRUSH}} = C_{\text{LOAD}} \times \frac{dV}{dt}$$

Where

$I_{\text{INRUSH}}$  = amount of inrush current caused by a capacitance

$C$  = total capacitance

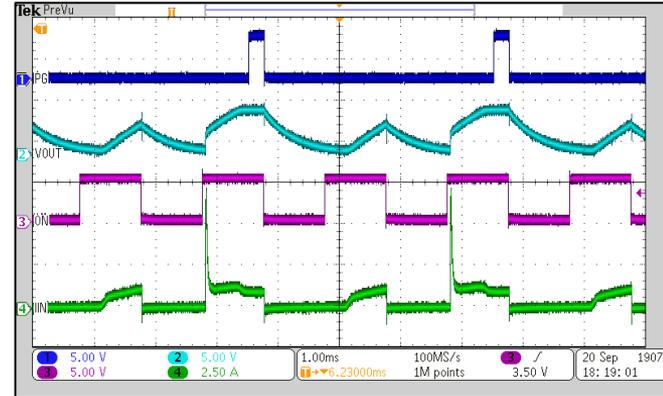
$dV$  = change in voltage during ramp up

$dt$  = rise time (during voltage ramp up)

- For example:  $C_{\text{OUT}} = 100 \mu\text{F}$  at 5V you want to limit at a max of 1A

$$T_R = \frac{100\mu\text{F} * 5\text{V}}{1\text{A}} = 500\mu\text{S}$$

- You will need a  $T_R$  of 500  $\mu\text{S}$  to keep the inrush current to 1A



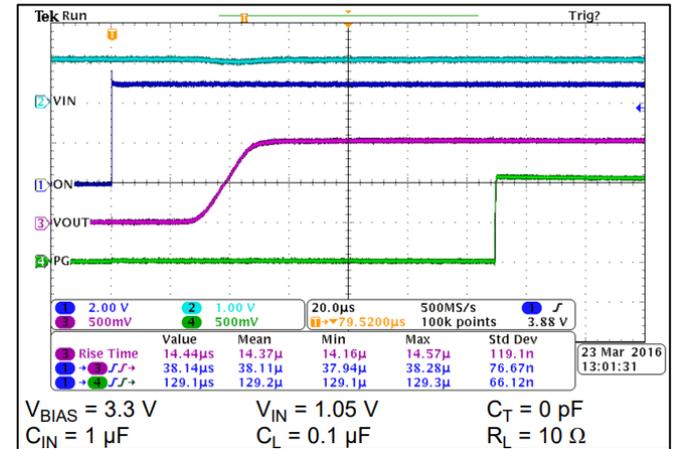
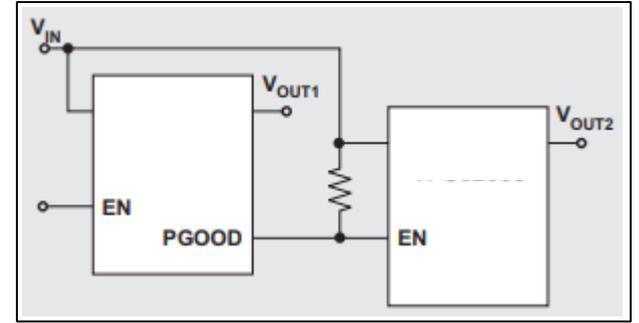
# Power good

## Functionality:

- Indicates that the **output voltage** of the device has risen to 90% of its final value. Some devices may have internal delays built in
- Open drain output

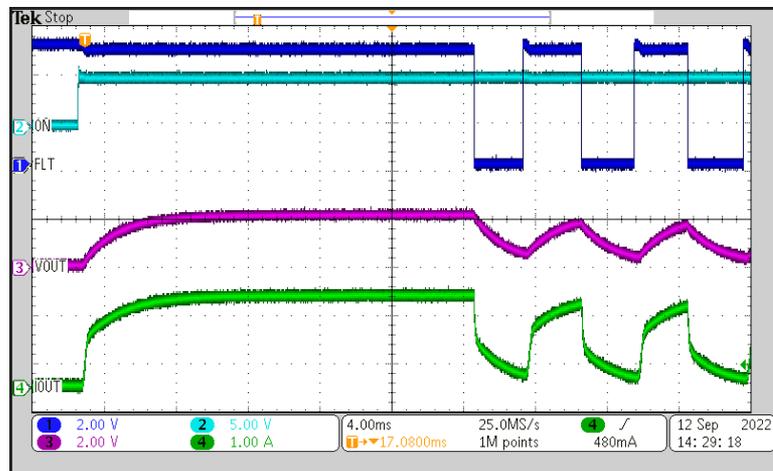
## Applications:

- Power sequencing (For example: DDR)
- Logic control (For example: power multiplexing)



# Thermal shutdown

- $T_{SD}$  **prevents** the junction temperature of the device from exceeding a fixed threshold to protect the device
- Includes auto-retry when  $T_J <$  falling temperature threshold

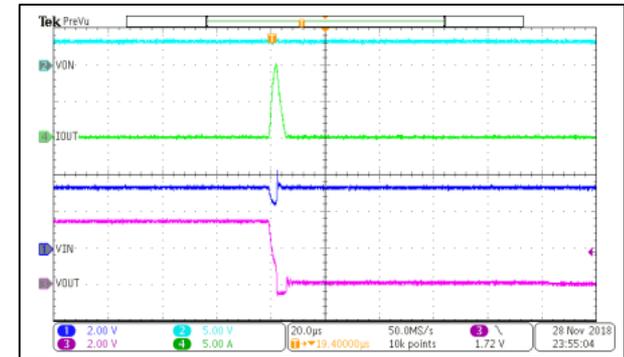
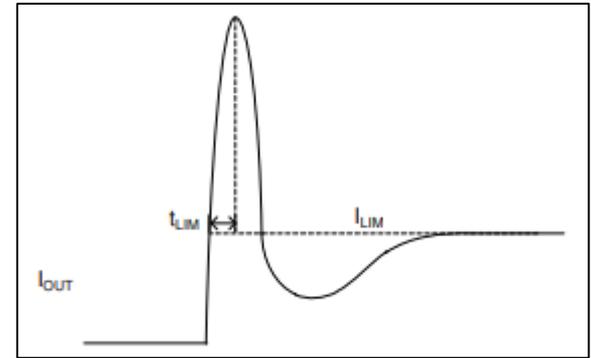


Thermal Shutdown (TSD)					
TSD	Thermal Shutdown	Rising	N/A	170	°C
		Falling (Hysteresis)	N/A	150	°C

TPS22950

# Short circuit protection (SCP) Vs. current limit

- SCP trigger method:  $V_{IN} - V_{OUT} > V_{SC}$  compares input and output voltage until it exceeds a specified amount and enters a regulation state.
- Current limit trigger method: Will have an integrated sense circuit that moves the device into a regulation state when current exceeds a specified value.
- Devices with the current limiting feature will also have SCP, but devices with SCP may not have current limiting.



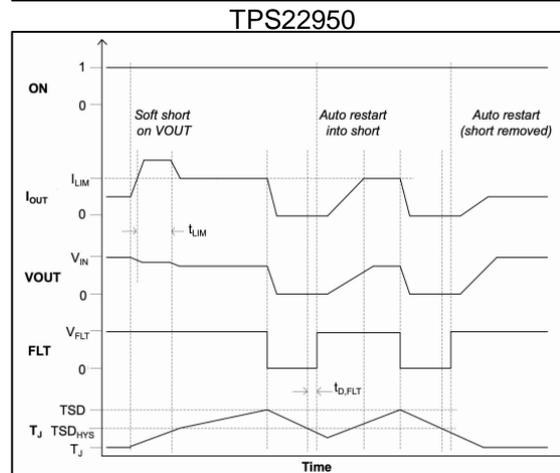
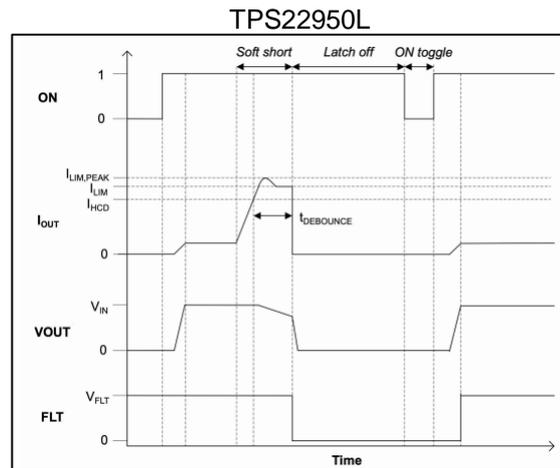
# Load switch current limiting

## Latch off current limit:

- Over current fault causes the device to turn off after a short period of current limiting at a set value until the ON pin is toggled

## Current regulation:

- Over current fault causes the device to limit at a set current value until the fault is removed or the device hits  $T_{SD}$



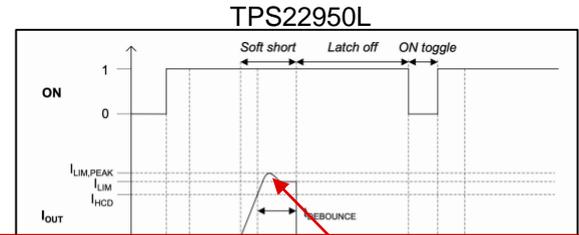
# Load switch current limiting

## Latch off current limit:

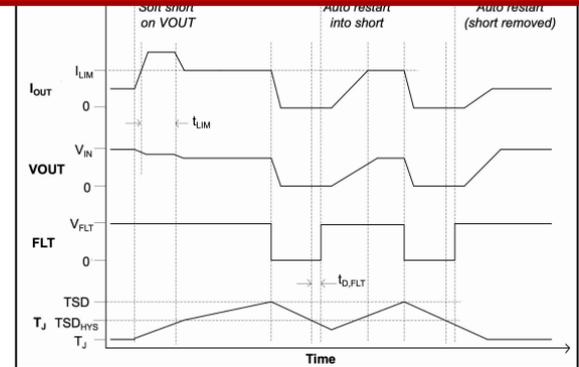
- Over current fault causes the device to turn off after a short period of current limiting at a set value until the ON pin is toggled

## Current limit hold:

- Over current fault causes the device to limit at a set current value until the fault is removed or the device hits  $T_{SD}$



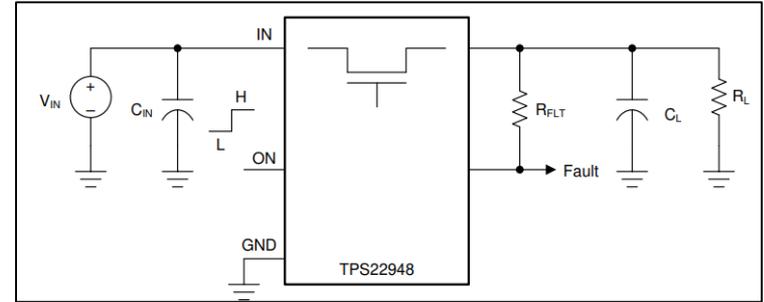
$I_{LIMPEAK}$  is the overshoot of current that occurs just before the current limit is engaged



# Load switch current limiting

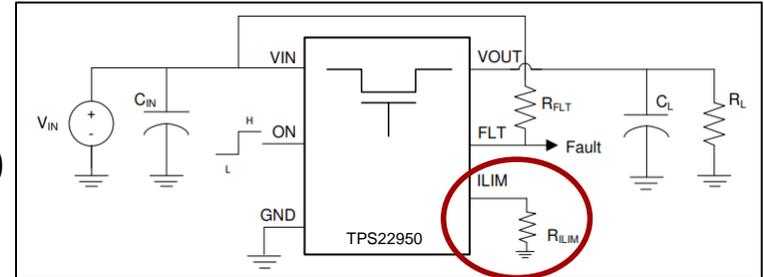
## Fixed current limit:

- Some devices have a fixed current limit such as the TPS2294x series



## Adjustable current limit:

- Other devices, through an " $I_{LIM}$ " pin, have an adjustable current limit such as the TPS22950



# Reverse current protection (RCP)

## RCP activation:

- For RCP to enable:  $V_{OUT} > V_{IN} + V_{RCP}$  where  $V_{RCP}$  is device specific and dependent on the  $R_{ON}$  of the device. This means some reverse current will occur

## RCP when disabled:

- When  $ON < V_{IL}$  the device enables RCP, otherwise it is disabled

## Always-ON RCP:

- Regardless of ON the device enables RCP

r <sub>ON</sub>	On-resistance	V <sub>IN</sub> = 5.25 V, I <sub>OUT</sub> = -200 mA	25°C	60	80
			Full		110
	V <sub>IN</sub> = 5.0 V, I <sub>OUT</sub> = -200 mA	25°C	60	80	
		Full		110	
	V <sub>IN</sub> = 4.2 V, I <sub>OUT</sub> = -200 mA	25°C	60	80	
		Full		110	
	V <sub>IN</sub> = 3.3 V, I <sub>OUT</sub> = -200 mA	25°C	60.7	80	
		Full		110	
	V <sub>IN</sub> = 2.5 V, I <sub>OUT</sub> = -200 mA	25°C	63.4	90	
		Full		120	
	V <sub>IN</sub> = 1.8 V, I <sub>OUT</sub> = -200 mA	25°C	74.2	100	
		Full		130	
V <sub>IN</sub> = 1.5 V, I <sub>OUT</sub> = -200 mA	25°C	83.9	120		
	Full		150		

$$V_{RCP} = 44mV$$

$$R_{ON} = 60m\Omega$$

$$I_{RCB} = \frac{44mV}{60m\Omega} = 733mA$$

V <sub>RCP</sub>	Reverse current voltage threshold	TPS22910A, TPS22913B/C	44	mV
		TPS22912C	54	

# Quick output discharge

## Benefits:

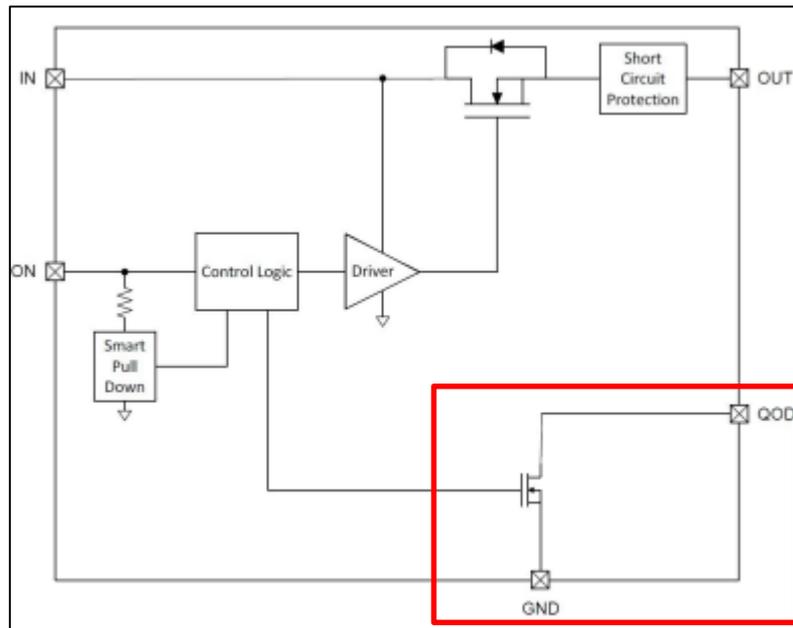
- QOD ties the output of the device to ground through resistance when  $V_{EN} < V_{IL}$
- Known state
- Ensures downstream devices are turned off

## Cons:

- Batteries and super charge capacitors on output
- Power multiplexing

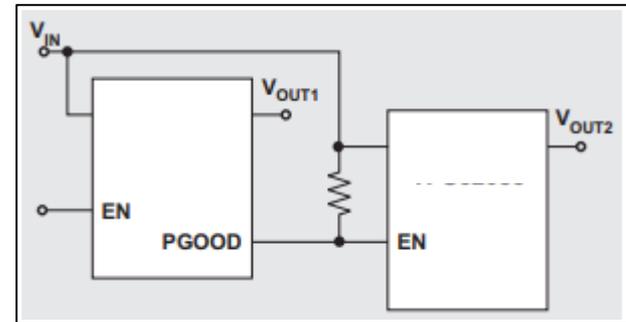
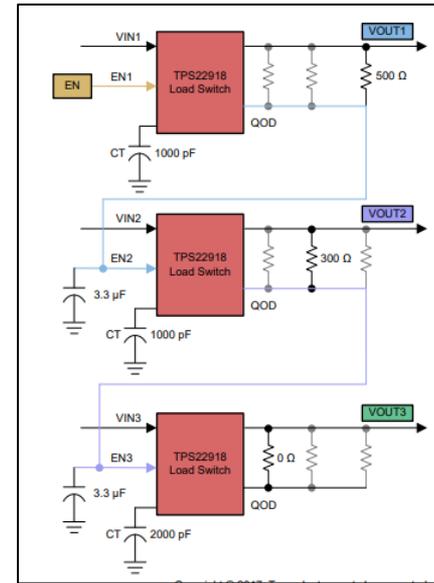
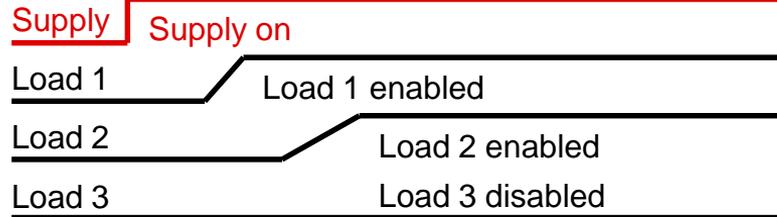
Equation for fall time:

$$t_f = R_{L||QOD} \times C_L \times \ln\left(\frac{V_{10\%}}{V_{90\%}}\right)$$



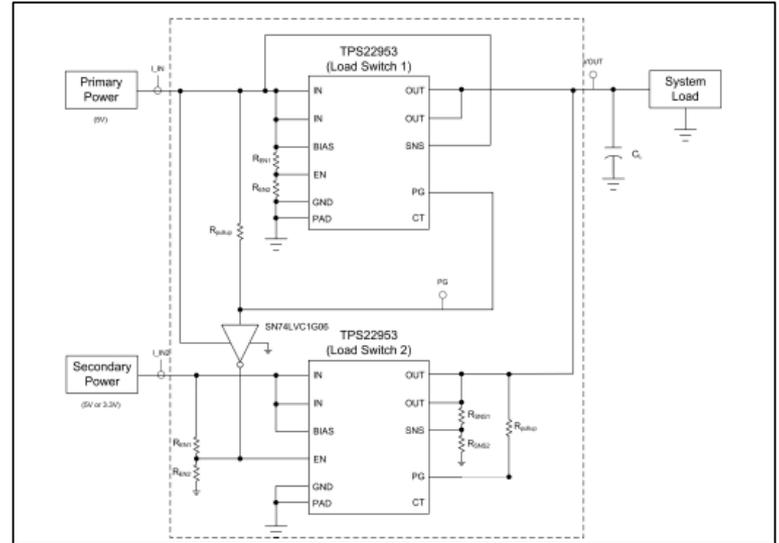
# Power sequencing

- Some applications require power rails to be enabled in a specific order
- Load switches can help achieve sequencing needs using PG, QOD or slew rate control

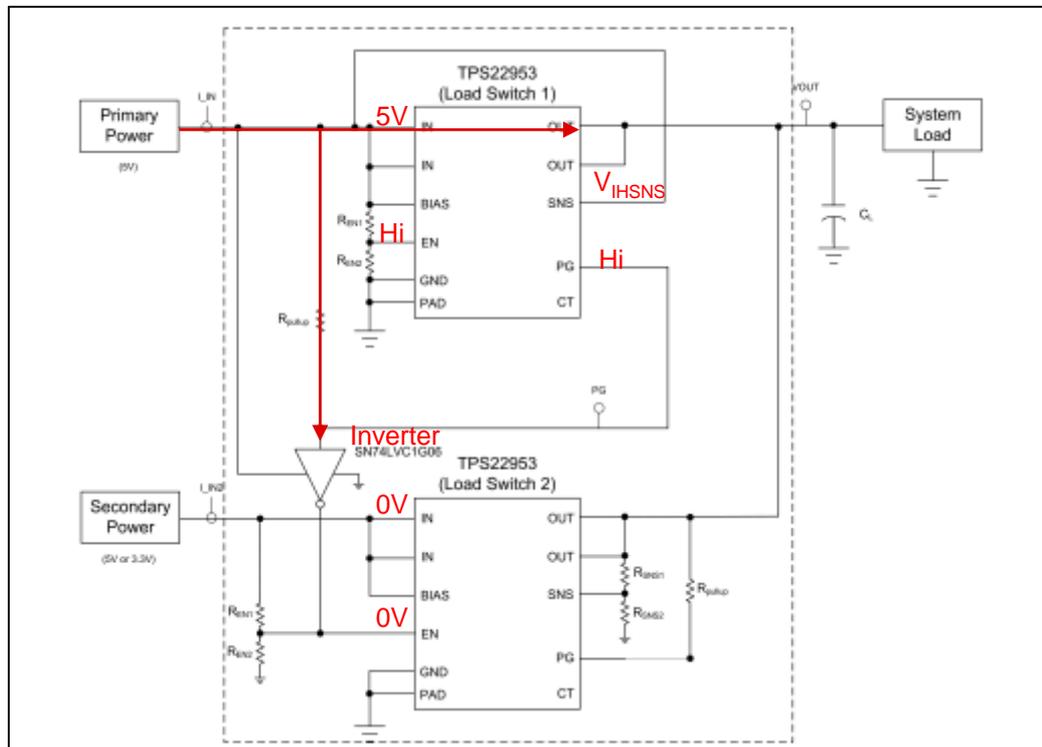


# Logic control

- Power multiplexing applications often require break-before-make logic to prevent feeding power back into supplies
- Using the PG pin of TPS22953 and an inverter we can create a logic control scheme for power multiplexing application to ensure only one switch is enabled at a time

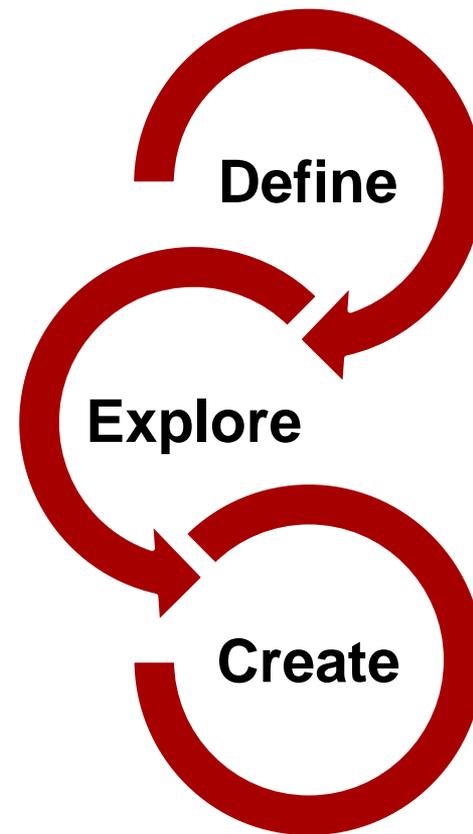
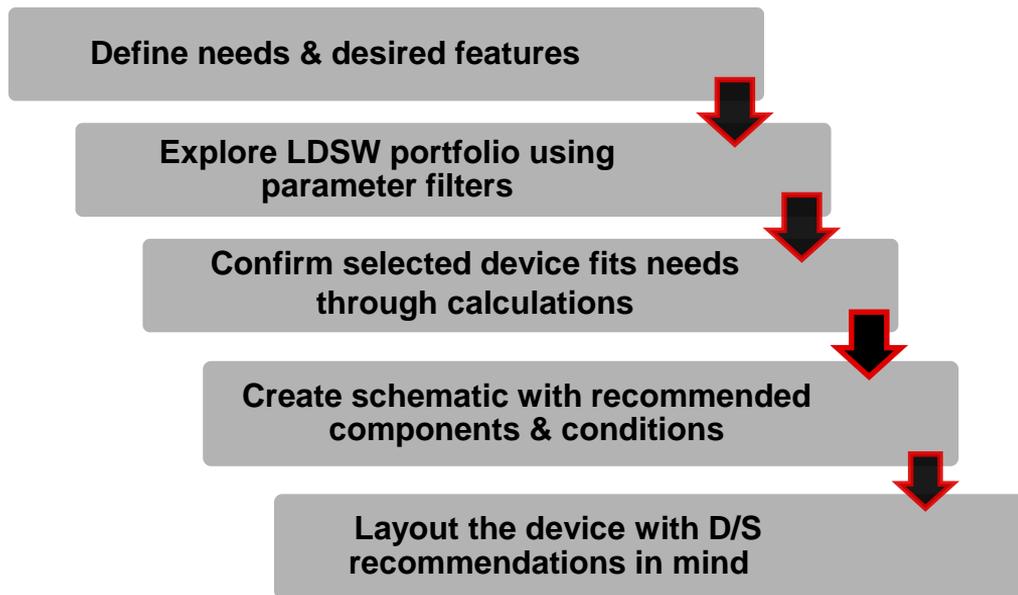


# Power good logic control





# Selecting a device



# Needs defined

## Device use case

---

- Power sequencing
- Inrush control

## System needs & parameters

---

- Small size
- RCP for upstream modules/supply
- QOD to keep downstream modules from floating
- Limit inrush current
- $C_L = 100\mu\text{F}$
- $V_{IN} = 5\text{V}$
- $R_L = 10\ \Omega$
- $I_{OUT} = 500\text{mA}$

✓ Features ^

- ON/OFF control
- Power good signal
- Quick output discharge
- Reverse current blocking
- Reverse current protection
- Reverse polarity

[View 9 parts](#)

[www.ti.com/loadswitches](http://www.ti.com/loadswitches)

# Selecting a device

9 matching parts out of 69 total parts | [Log in to view inventory](#) [Log in](#)

Compare	Part Number <input type="text" value="Filter by part number"/>	Number of channels (#)	Vin (Min) (V)	Vin (Max) (V)	Approx. price (USD)	I <sub>max</sub> (A)	Ron (Typ) (mOhm)	Shutdown current (ISD) (Typ) (uA)	Quiescent current (Iq) (Typ) (uA)	Soft start	Rise time (Typ) (us)	Current limit type	Features
<input type="checkbox"/>	TPS22968 - 2-ch, 5.5-V, 4-A, 25-mΩ load switch with adj. rise time and output discharge	2	0.8	5.5	\$0.293   1ku	4	25	0.5	55	Adjustable Rise Time	65	None	Quick output discharge, Reverse current protection
<input type="checkbox"/>	TPS22968-Q1 - 2-ch, 5.5-V, 4-A, 27-mΩ, automotive load switch with adj. rise time and output discharge	2	0.8	5.5	\$0.346   1ku	4	27	0.5	55	Adjustable Rise Time	65	None	Quick output discharge, Reverse current protection
<input type="checkbox"/>	TPS22925 - 3.6-V, 3-A, 9.2-mΩ load switch with output discharge	1	0.65	3.6	\$0.173   1ku	3	10.3	0.5	60	Fixed Rise Time	61	None	Inrush current control, Quick output discharge, Reverse current protection
<input type="checkbox"/>	TPS22964C - 5.5-V, 3-A, 14-mΩ load switch with output discharge	1	1	5.5	\$0.243   1ku	3	13.8	0.76	38	Fixed Rise Time	890	None	Quick output discharge, Reverse current protection
<input type="checkbox"/>	TPS22950 - 5.5-V, 2-A, 40-mΩ load switch with adjustable current limit	1	1.8	5.5	\$0.200   1ku	2.7	40	0.2	40	Fixed Rise Time	550	Adjustable	Quick output discharge, Reverse current protection, Short circuit protection, Thermal shutdown
<input type="checkbox"/>	TPS22916 - 5.5-V, 2-A, 60-mΩ, 10-nA leakage load switch with output discharge	1	1	5.5	\$0.112   1ku	2	60	0.01, 0.1	0.5	Adjustable Rise Time	65, 900	None	Active low, Quick output discharge, Reverse current protection
<input type="checkbox"/>	TPS22917 - 5.5-V, 2-A, 80-mΩ, 10-nA leakage load switch adj. rise time and adj output discharge	1	1	5.5	\$0.141   1ku	2	80	0.01	0.5	Adjustable Rise Time	55	None	Quick output discharge, Reverse current protection
<input type="checkbox"/>	TPS22913 - 5.5-V, 2-A, 60-mΩ load switch with output discharge	1	1.4	5.5	\$0.207   1ku	2	61	10	2	Fixed Rise Time	82, 838	None	Inrush current control, Quick output discharge, Reverse current protection, Under voltage lock out
<input type="checkbox"/>	TPS22929D - 5.5-V, 1.8-A, 115-mΩ load switch with output discharge	1	1.4	5.5	\$0.232   1ku	1.8	115	10	2	Fixed Rise Time	3660	None	Inrush current control, Quick output discharge, Reverse current protection, Under voltage lock out

# Selecting a device

## Devices

- TPS22916B – 70µS  $t_r$  with QOD and active high
- TPS22916BL – 70µS  $t_r$  with QOD and active low

### 6.6 Switching Characteristics

Unless otherwise noted, the typical characteristics in the following table applies over the entire recommended power supply voltage range of 1 V to 5.5 V at 25°C with a load of  $C_L = 0.1\mu\text{F}$ ,  $R_L = 10\Omega$ .

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
TPS22916B, TPS22916BL					
$t_{ON}$	Turn On Time	$V_{IN} = 5\text{ V}$		115	$\mu\text{s}$
		$V_{IN} = 3.6\text{ V}$		140	
		$V_{IN} = 1.8\text{ V}$		250	
		$V_{IN} = 1.2\text{ V}$		350	
		$V_{IN} = 1\text{ V}$		510	
$t_{RISE}$	Rise Time	$V_{IN} = 5\text{ V}$		70	$\mu\text{s}$
		$V_{IN} = 3.6\text{ V}$		80	
		$V_{IN} = 1.8\text{ V}$		130	
		$V_{IN} = 1.2\text{ V}$		190	
		$V_{IN} = 1\text{ V}$		240	

$$I_{rush\text{Current}} = \frac{100\mu\text{F} * 5\text{V}}{70\mu\text{S}} = 7.14\text{A}$$

$I_{MAX} = 7.64\text{ A}$  outside of specifications



# Selecting a device

## Devices

- TPS22916C – 800 $\mu$ S  $t_r$  with QOD and active high
- TPS22916CN – 800 $\mu$ S  $t_r$  without QOD and active high
- TPS22916CL – 800 $\mu$ S  $t_r$  with QOD and active low
- TPS22916CNL – 800 $\mu$ S  $t_r$  without QOD and active low

### 6.6 Switching Characteristics (continued)

Unless otherwise noted, the typical characteristics in the following table applies over the entire recommended power supply voltage range of 1 V to 5.5 V at 25°C with a load of  $C_L = 0.1\mu\text{F}$ ,  $R_L = 10\Omega$ .

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
TPS22916C, TPS22916CN, TPS22916CL, TPS22916CNL					
$t_{ON}$	Turn On Time	$V_{IN} = 5\text{ V}$	1400		$\mu\text{s}$
		$V_{IN} = 3.6\text{ V}$	1700		
		$V_{IN} = 1.8\text{ V}$	3000		
		$V_{IN} = 1.2\text{ V}$	5000		
		$V_{IN} = 1\text{ V}$	6500		
$t_{RISE}$	Rise Time	$V_{IN} = 5\text{ V}$	800		$\mu\text{s}$
		$V_{IN} = 3.6\text{ V}$	900		
		$V_{IN} = 1.8\text{ V}$	1400		
		$V_{IN} = 1.2\text{ V}$	2300		
		$V_{IN} = 1\text{ V}$	3000		

$$I_{rush\ current} = \frac{100\mu\text{F} * 5\text{V}}{800\mu\text{S}} = 625\text{mA}$$
$$I_{MAX} = 1.125\text{ A within specifications}$$



# Thermal calculations

## Power dissipation

$$P_D = I_{LOAD}^2 \times R_{ON}$$

$$P_D = 0.5^2 \times 80 = 20mW$$

## Thermal resistance

$$T_J = R_{\theta JA} \times P_D + T_A$$

$$T_J = 193 \times 0.02 + 25 = 28.9 \text{ } ^\circ\text{C}$$

## Considerations

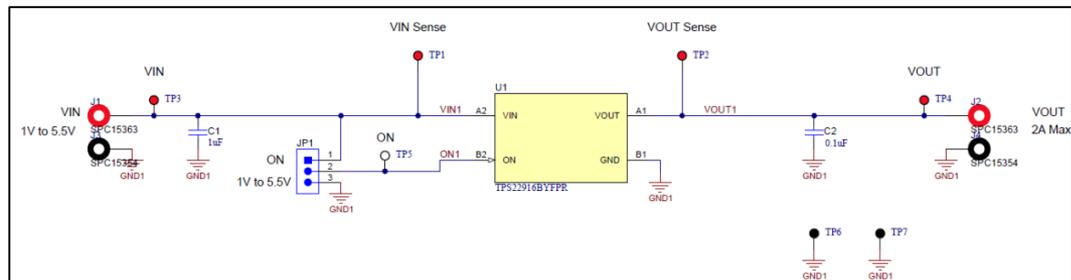
$R_{\theta JA}$  is based on a JEDEC standard board with thin power traces and limited thermal dissipation. It's also helpful to get a general idea of a devices thermal performance, but can be significantly improved through methods mentioned in the layout section

ON-RESISTANCE ( $R_{ON}$ )						
$R_{ON}$	ON-Resistance	$I_{OUT} = 200 \text{ mA}$	$V_{IN} = 5 \text{ V}$	25°C	60 80	mΩ
				-40°C to +85°C	100	
				-40°C to +105°C	120	
			$V_{IN} = 3.6 \text{ V}$	25°C	70 90	
				-40°C to +85°C	120	
				-40°C to +105°C	140	
			$V_{IN} = 1.8 \text{ V}$	25°C	100 125	
				-40°C to +85°C	150	
				-40°C to +105°C	175	
			$V_{IN} = 1.2 \text{ V}$	25°C	150 200	
				-40°C to +85°C	250	
				-40°C to +105°C	300	
			$V_{IN} = 1 \text{ V}$	25°C	200 275	
				-40°C to +85°C	325	
				-40°C to +105°C	375	

Thermal Parameters <sup>(1)</sup>		TPS22916xx	UNIT
		YFP (WCSP)	
		4 PINS	
$\theta_{JA}$	Junction-to-ambient thermal resistance	193	°C/W
$\theta_{JCl\text{op}}$	Junction-to-case (top) thermal resistance	2.3	°C/W
$\theta_{JB}$	Junction-to-board thermal resistance	36	°C/W
$\psi_{JT}$	Junction-to-top characterization parameter	12	°C/W
$\psi_{JB}$	Junction-to-board characterization parameter	36	°C/W

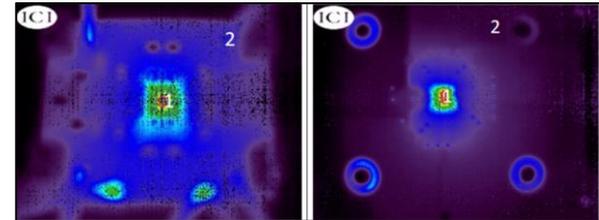
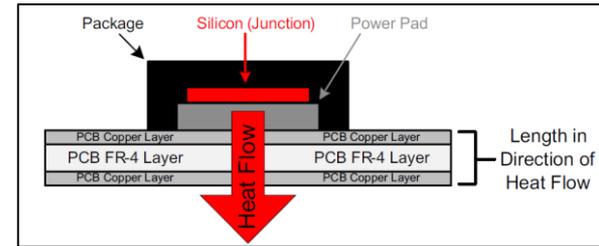
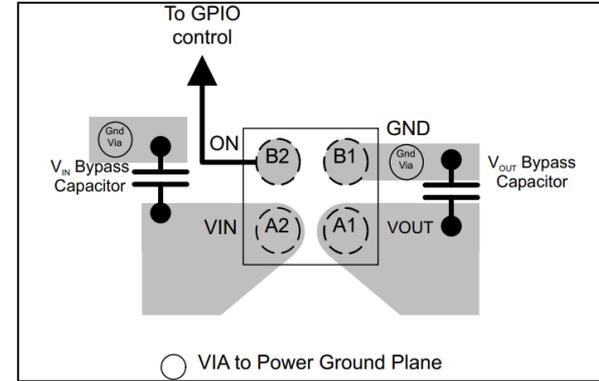
# Schematic

- $C_{IN}$  –  $1\mu\text{F}$  recommended
- $C_{OUT}$  –  $0.1\mu\text{F}$  recommended
- $C_{IN}:C_{OUT}$  – 10:1 ratio for weak supplies that are unable to provide inrush current without dropping in voltage
- These are recommendations but not mandatory for device performance



# Layout

- Polygon pour planes
- Via stitching GND pour to GND plane
- Capacitance close to pins minimizes current loops
- Copper and FR-4 layer thickness & amount of layers connected to increases the devices ability to dissipate heat
- Board area increases have diminishing returns



# Load types

## Capacitive

- Inrush current is the main concern as shown previously
- Weak supplies are concerning with significant output capacitance

## Resistive

- Maintaining conditions within recommended specifications when including base  $R_L$  and any inrush current or inductive swinging from line inductance

## Inductive

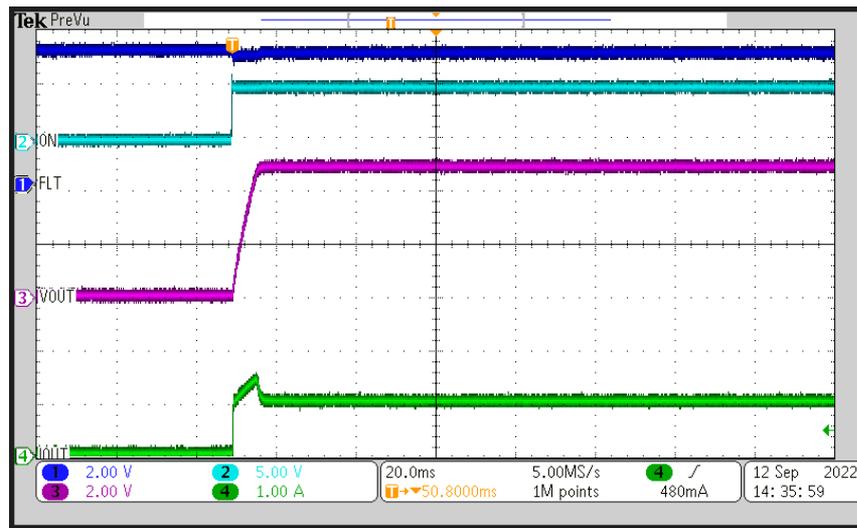
- Not recommended with load switches as there isn't a  $V_{DS}$  clamp; however, possible provided other protections in place exterior to the load switch



# Capacitor charging

**Slew rate control:** Significant inrush current due to capacitance can be controlled by controlling the slew rate of the output voltage, preventing significant spikes in current to charge capacitors.

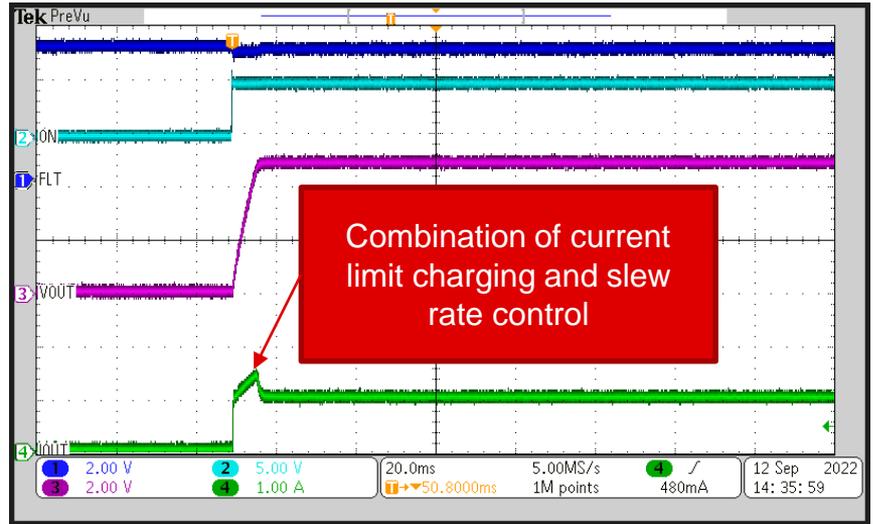
**Current limit:** Allowing the device to charge a capacitor quickly by limiting the current at a set value



# Capacitor charging

**Slew rate control:** Significant inrush current due to capacitance can be controlled by controlling the slew rate of the output voltage, preventing significant spikes in current to charge capacitors.

**Current limit:** Allowing the device to charge a capacitor quickly by limiting the current at a set value



# Automotive Standards & Specifications

- AEC-Q100 is an automotive standard that specifies the stress test qualifications a device must pass without any true failures
- ISO, and IEC specifications do not apply since supply is from DC/DC & load is on same ECU

**AEC - Q100-007** - Fault Simulation and Test Grading

**AEC - Q100-008** - Early Life Failure Rate (ELFR)

**AEC - Q100-009** - Electrical Distribution Assessment

**AEC - Q100-010** - Solder Ball Shear Test

**AEC - Q100-011** - Charged Device Model (CDM) Electrostatic Discharge Test

**AEC - Q100-001** - Wire Bond Shear Test

**AEC - Q100-002** - Human Body Model (HBM) Electrostatic Discharge Test

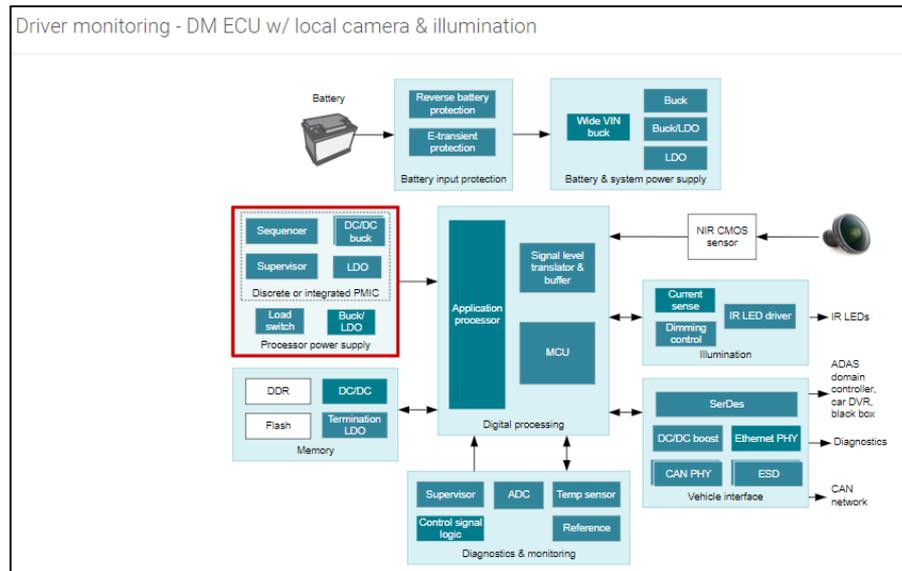
**AEC - Q100-004** - IC Latch-Up Test

**AEC - Q100-005** - Non-Volatile Memory Program/Erase Endurance, Data Retention, and Operational Life Test

**AEC - Q100-012** - Short Circuit Reliability Characterization of Smart Power Devices for 12V Systems

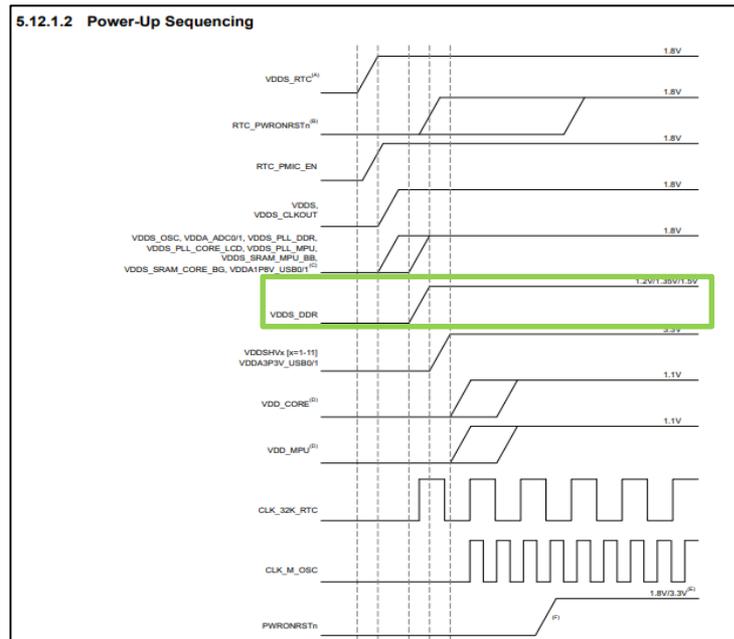
# ADAS specific design

- DC/DC buck (12V lead acid battery to 3.3V)
- Load switch enables rail to processor for DDR
- Supply/load on same ECU
- AEC-Q100 requirement



# DDR requirements

- Voltage requirements: 1.5V & 3.3V
- Current requirement: 300mA
- Power sequencing
- TPS22995H-Q1

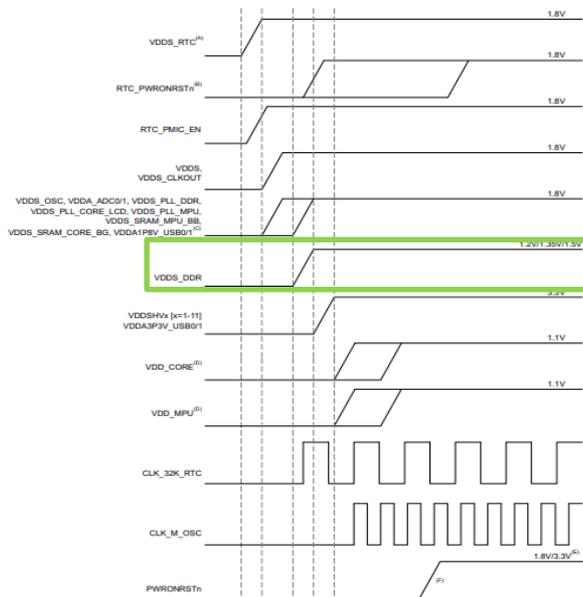


NO.	PARAMETER	MIN	MAX	UNIT	
1	VDDS_DDR bulk bypass capacitor count	2		Devices	
2	VDDS_DDR bulk bypass total capacitance	20		μF	
VDDS_DDR	Supply voltage range for DDR IO domain (DDR3)	1.425	1.500	1.575	V
	Supply voltage range for DDR IO domain (DDR3L)	1.283	1.350	1.418	
	Supply voltage range for DDR IO domain (LPDDR2)	1.140	1.200	1.260	
VDDS_DDR	Maximum current rating for DDR IO domain; DDR3/DDR3L		300	mA	
	Maximum current rating for DDR IO domain; LPDDR2		150		

# DDR requirements

- Voltage requirements: 1.5V & 3.3V
- Current requirement: 300mA
- Power sequencing
- TPS22995H-Q1

5.12.1.2 Power-Up Sequencing

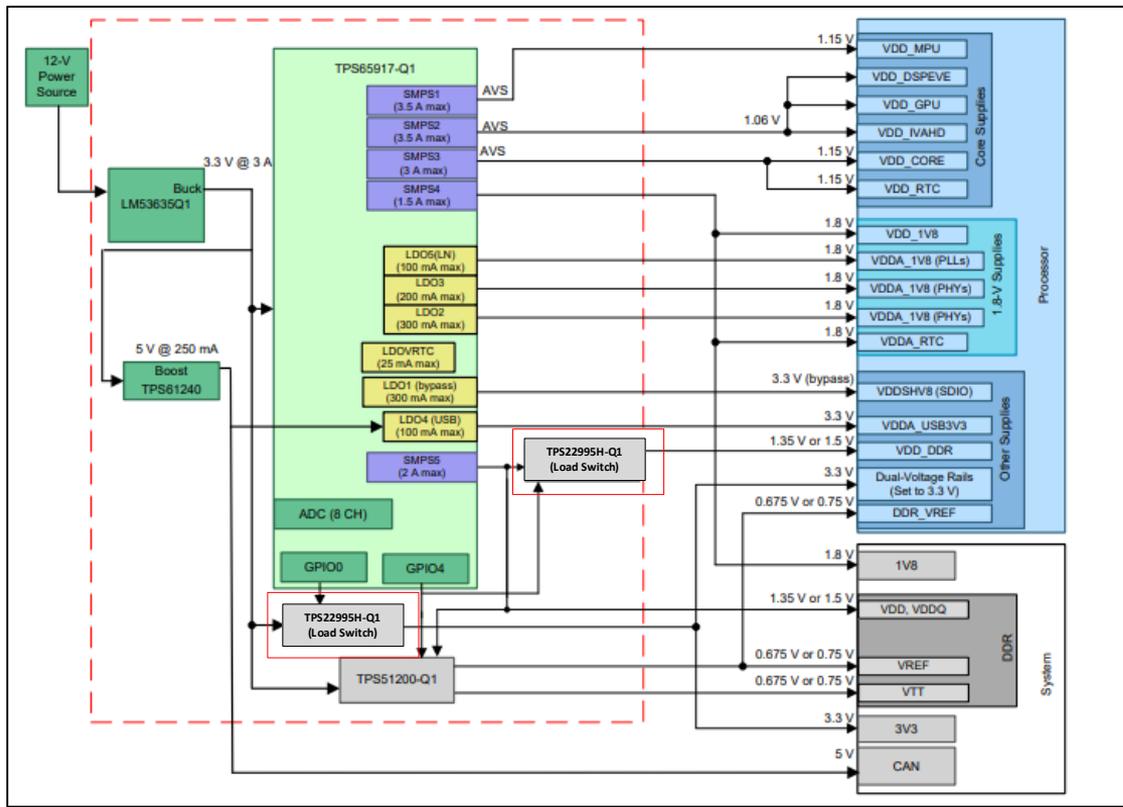


## 6.3 Recommended Operating Conditions TPS22995H-Q1

over operating free-air temperature range (unless otherwise noted)

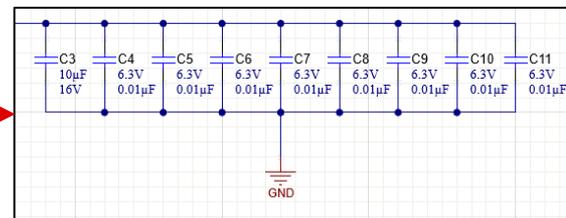
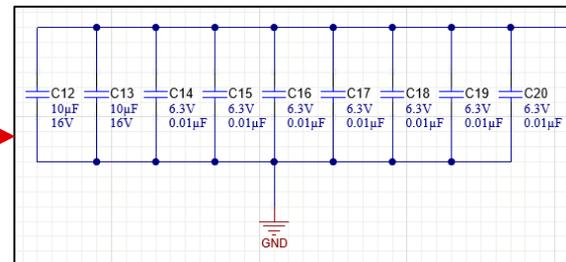
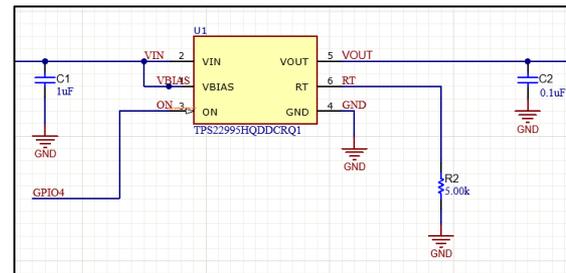
		MIN	NOM	MAX	UNIT
$V_{IN}$	Input Voltage	0.8		5.5	V
$V_{BIAS}$	Bias Voltage	1.5		5.5	V
$V_{IH}$	ON Pin High Voltage Range	0.8		5.5	V
$V_{IL}$	ON Pin Low Voltage Range	0		0.35	V
$T_A$	Ambient Temperature	-40		125	°C

# ADAS block diagram



# ADAS TPS22995H-Q1 schematic

- $V_{IN}$  and  $V_{BIAS}$  are tied together and supplied by SMPS5 of PMIC
- GPIO4 controls ON signal to power sequence the device
- Bulk capacitance on output of PMIC ensures the rail doesn't dip in voltage when power is provided
- Bypass capacitors are required near processor DDR input pin (usually on topside/backside of processor)



# ADAS TPS22995H-Q1 layout

- Polygon pours for  $V_{IN}/V_{OUT} > 0.5$   
 $I_n^2$
- $C_{IN}$  and  $C_{OUT}$  capacitors as close to  $V_{IN}$  and  $V_{OUT}$  pins as possible
- GND polygon pour with vias to GND plane
- RT resistor placed close to RT pin

